SOT1930-1

SIL3, plastic DIL-bent-SIL package, 3 terminals; 5.44 mm pitch; 15.92 mm x 20.96 mm x 5.07 mm body

15 April 2019 Package information

1 Package summary

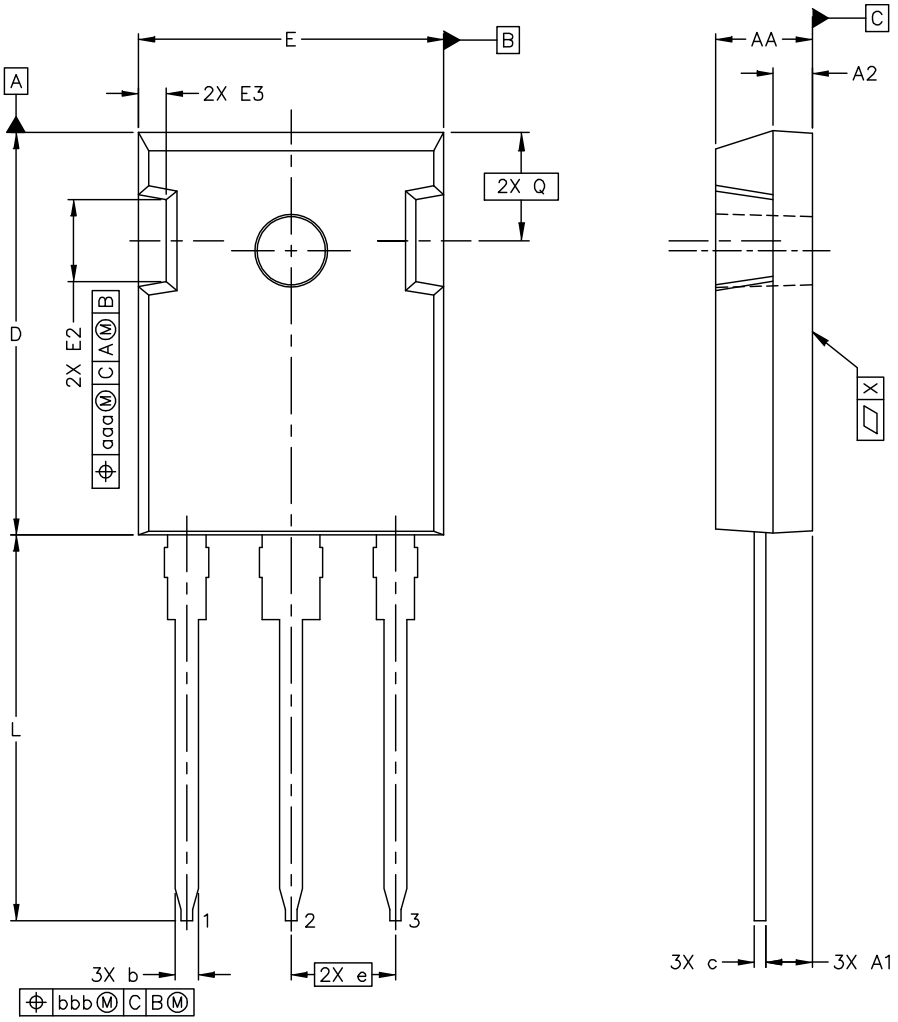
Terminal position code	Z (zig-zag)
Package type descriptive code	SIL3
Package style descriptive code	DBS (DIL-bent-SIL)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	13-02-2019
Manufacturer package code	98ASA01082D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	15.92	-	mm
package width	-	20.96	-	mm
package height	-	5.07	-	mm
nominal pitch	-	5.44	-	mm
actual quantity of termination	-	3	-	

SIL3, plastic DIL-bent-SIL package, 3 terminals; 5.44 mm pitch; 15.92 mm x 20.96 mm x 5.07 mm body

2 Package outline



DATE: 13 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01082D	REVISION: A	

Figure 1. Package outline SIL3 (SOT1930-1)

SIL3, plastic DIL-bent-SIL package, 3 terminals; 5.44 mm pitch; 15.92 mm x 20.96 mm x 5.07 mm body

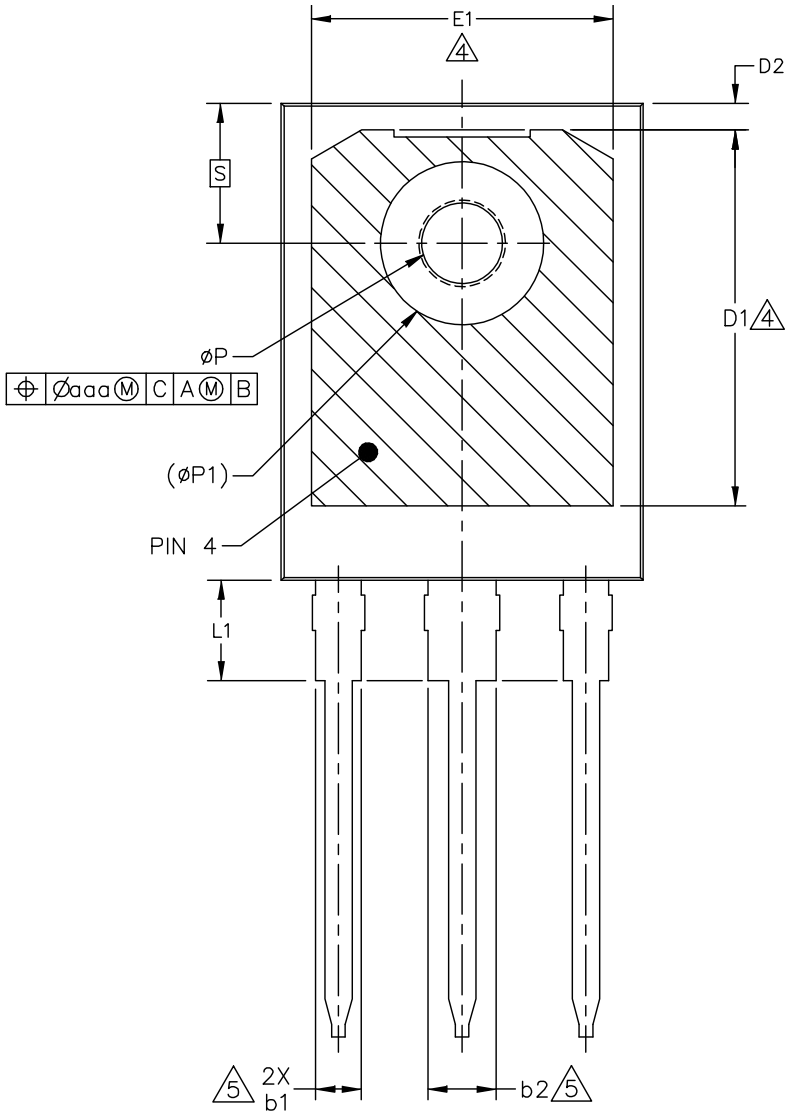


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Figure 2. Package outline dt SIL3 (SOT1930-1)

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NOTES:

1. CONTROLLING DIMENSION: MILLIMETER, ANGLES ARE IN DEGREES.
2. INTERPRET DIMENSIONS AND TOLERANCES AS PER ASME Y14.5M–1994.
3. DIMENSION D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 MM (.005 INCH) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
4. HATCHING REPRESENTS THE EXPOSED AREA OF THE THERMAL PAD (PIN 4). DIMENSIONS D1 AND E1 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF THE EXPOSED AREA OF THE THERMAL PAD. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION D1 AND E1.
5. DIMENSIONS b1 & b2 DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.15 MM (.006 INCH) PER SIDE IN EXCESS OF THE DIMENSIONS b1 & b2 AT MAXIMUM MATERIAL CONDITION.
6. EJECTOR MARKS ON TOP SURFACE ARE PERMITTED AND IT IS SUPPLIER OPTION. THE MAXIMUM DEPTH OF EJECTOR MARK IS 0.25 MM (.010 INCH)
7. ø P TO HAVE MAXIMUM DRAFT ANGLE 1.5°.

DIM	INCH MIN	INCH MAX	MILLIMETER MIN	MILLIMETER MAX	DIM	INCH MIN	INCH MAX	MILLIMETER MIN	MILLIMETER MAX
AA	.190	.205	4.83	5.21	E3	.039	.102	0.99	2.60
A1	.090	.100	2.29	2.54	e	.214 BSC		5.44 BSC	
A2	.075	.085	1.90	2.16	L	.780	.800	19.80	20.32
b	.042	.052	1.07	1.33	L1	---	.173	---	4.40
b1	.075	.095	1.91	2.41	P	.138	.146	3.50	3.71
b2	.113	.133	2.87	3.38	P1	---	.291	---	7.40
c	.022	.027	0.55	0.69	Q	.228 BSC		5.79 BSC	
D	.819	.831	20.80	21.11	S	.242 BSC		6.15 BSC	
D1	.515	---	13.08	---	X	---	.004	---	0.01
D2	.020	---	0.51	---	aaa	.025		0.64	
E	.618	.635	15.70	16.13	bbb	.010		0.25	
E1	.487	---	12.37	---					
E2	.145	.201	3.68	5.11					

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Figure 3. Package outline note SIL3 (SOT1930-1)

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For more information, please visit: http://www.nxp.com
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